

**TRUST**  
**IDTechEx**



Printed  
Electronics  
WORLD  
EUROPE06

**...IMAGINE THE POSSIBILITIES**

**19-21 APRIL 2006, CHURCHILL COLLEGE, CAMBRIDGE UK**  
[www.printelec.com](http://www.printelec.com)

**WELCOME TO THE PRODUCTS OF THE FUTURE.**

**Converging Printing with Electronics; The New Era for the  
Printing Industry.**

A truly global conference in the heart of the UK's Science and Innovation Hub, the 2<sup>nd</sup> Printed Electronics uniquely covers the Big Picture.

Organic & Printed Inorganic Semiconductors  
Markets, Potential Users and Applications  
Sensors, Sound, Power and Photovoltaics  
Display Technology  
Manufacture Techniques

Exclusive Tours; Visit Plastic Logic and The Technology Partnership (TTP) Sites

**Exhibition space from £2000 + VAT**

## About Printed Electronics.

The market for organic and printable electronics is expected to reach \$300BN in 2025 – larger than the size of the silicon industry today. The future electronic fabrication plants will be printing processes. Enormous markets will be created where conventional silicon chips cannot go today because they are too brittle. A full range of electrical and electronic components will be printed – from transistor circuits to displays, power and even speakers.

Uniquely, Printed Electronics World will also cover the Global Picture;

- The application of the emerging printed electronics toolkit
- progress in displays, thin film transistor circuits, sensors, power and sound
- global developments from companies around the world
- materials and manufacturing techniques
- Investing in printed/organic electronics

## Who Attends

**Over 600 companies have benefited from our Printed Electronics events.  
See back page for details**

**Europe 2005 attracted over 180 delegates from over 20 countries including;**

**USA, UK, Sweden, Japan, Belgium, Germany, France, Finland, Austria, Netherlands, Ireland, Italy, Israel, Taiwan, Denmark, Singapore, Canada, Korea, Greece, Russia**

## **Type of Delegate**

- **End Users**
- **CPG's**
- **Packaging Developers**
- **Brand Managers**
- **Product Designers**
- **Graphic Designers**
- **Electronics Architects**
- **Technology Developers**
- **Print Technology Developers**
- **Materials Developers**
- **Label Makers**

## **Job titles:**

**Chairman, CEO, CIO, CTO, President, Managing Director, General Manager, Vice President, Director, Head of Operations, head of Development, Product/brand Director**



## Exhibition and Speaking Opportunities

**Display, Demonstrate, Speak, Meet, Network and Do Business.**

**Sponsorship provides you with a unique platform to showcase your products and services to a world-class level of attendee. Exhibition space is limited to 17 companies ensuring maximum exposure and opportunities to demonstrate, display, test and showcase.**

> **Bronze Sponsorship** Tabletop exhibition space for display and demonstrations are available from **£2000**

> **Silver Sponsorship** including speaker slot and tabletop from **£4500**

> **Gold Sponsorship** including speaker slot and tabletop and special packages from **£7000**

Prices exclude VAT

**Also available;**

**Dinner Sponsor > Master Class Sponsor > Badge Sponsor**

**! Book Your Sponsorship for Europe and USA events at the same time and Save 20% !**

**Don't forget to join our famous meet the Experts networking Dinner at St John's College Cambridge 20<sup>th</sup> April.**



**Imagine the possibilities..... Printed Electronics World**

**19-21 April, Cambridge UK**

**[www.printelec.com](http://www.printelec.com) [n.bateman@idtechex.com](mailto:n.bateman@idtechex.com) + 44 1223 810276**

## Previous delegates have included;

3M, Acheson Industries (Europe) Ltd, Advanced Research Laboratory, Hitachi, Ltd., Agfa-Gevaert NV, Air Products & Chemicals, Inc., ALPS Electric North America, American Dye Source, Inc., Appleton Coated, Applied Materials, ARC/Newco, Arccure Technologies GmbH, Areva FCI, Argent International, ArjoWiggins R&D, Artificial Muscle, Inc., Asahi-KASEI, Ashland, ASK, Aspocomp, Assa Abloy ITG, AT&S, Avantone Oy, Avery Dennison, Aveso Printed Electronic Displays, AVT, BAE Systems, BASF Future Business GmbH, Bayer Films Americas, BE Semiconductor Industries, Boeing, Bourns Inc, Bowater Inc., Brady Corporation, Brother International Corporation, Bundesdruckerei GmbH, C G Lazarakis SA, Cabot Corporation, Cambridge Display Technology, Cambrios Technologies, Canon, Caraustar Custom Packaging Group, Carvajal S.A., Cascades Folding Cartons, CEA, Cedinsa SA, Cenamps, Centre Microélectronique de Provence, Cerbo Group, Chemnitz University of Technology, Ciba Specialty Chemicals Inc, Cima NanoTech, Cintelliq Ltd, Coates Screen, Coding Products, Columbia University, Conductive Inkjet Technology, CIT, Cookson Electronics, Coors Brewing Company, Corning, Corus Research Development & Technology, COVEME SPA, CSAT America LLC, Cummins Allison, Cymbet Corporation, Cypak AB, Dai Nippon Printing Co., Ltd., Data2, De La Rue Group , Degussa AG, DEK Printing Machines Ltd, Diageo, Dimatix, Inc, DMATEK, Dow Corning Corporation, DuPont, Ecole des Mines, Electrox Corp, Elementis Specialties, elumin8 Systems, EMD Chemicals, Emerson & Cuming, Emphasis Materials Inc, ENEA, Episys, Epson, ERSO/ITRI, ETRI, Fotango, Fraunhofer Inst, FrontCoat Technologies, General Mills, Georgia Institute of Technology, Giesecke & Devrient , Givaudan, GlaxoSmithKline, Glud & Marstrand, GPV, Graphic Controls, Graphic Solutions , Group InfoTech, Gyricon, H C Starck, Hallmark Cards, Hammer Lithograph, Harris Corporation, Hewlett Packard, Honeywell, IBM, ICI, IIC Industrial Investment Council, IM3D Limited, Imperial College, Infineon Technologies, InkTec Co., International Paper, IRF, IT Strategies, Item IQ, ITN Energy Systems, ITW Tech Center, J2 Technology Consulting, Johnson & Johnson, KCL, KDDI R&D Laboratories, Kester, Kimberly-Clark, KIMM, Kodak, Kontogeorgis Packaging, Korea Institute of Machinery and Materials, Kovio, Kraft Foods , KSG Leiterplatten, Label Design., LANXESS, Leo Paper Group, Leonhard Kurz, LG Chem, LS Industrial Systems, MacDermid, MacDonald and Evans, MAN Roland ,Max Daetwyler, MDC Max Daetwyler, MeadWestvaco, Menlo Worldwide, Merck Chemicals, Meyers, Microdrop Technologies GmbH, Ministry of Defence, Mitsubishi, Motorola, M-Real Corporation, MRL/ITRI, Technologies AG, Nanosolar., Nanotechnologies,, NASA - Johnson Space Center, NCR , Nedap , Neopost Industrie, New Transducers Limited (NXT), Nielsen Media Research, Nissan Chemical Industries, Nitto Denko, Nokia, Novalia, NV Bekaert SA, OAA - Outdoor Advertising Association, OMET, Omron, Orbotech, Oregon State University, Orfid Corp, OrganicID, OTB, Oticon A/S, Outrider Technologies, Oxford University, PakSense, Panasonic Technologies Boston Laboratory, Panipol, Parelec, Parlex Corp., Poly-Flex Circuits, Partech, Paru, Patterning Technologies, PChem, , Pelikon, PERA Innovation, Philips, PicoJet, Pira, Pitney Bowes, Pivotal, Plastic Logic, Plextronics, PM USA, Polyera , Poly-Flex Circuits , PolyIC , Potters, Power Paper, Precision Press, Print Action, Printexs, Printpack Incorporated, Procter & Gamble, PT in DLR, Pulp & Paper Research Inst of Canada PAPRICAN, QinetiQ Metal Printing, QuantumSphere, Radial Energy Technologies, RATP, Ricoh Innovations, Rieke Metals, River Capital Markets, Rohm and Haas, RollsPack Pty, Saatiprint, Samsung, Sandia National Laboratories, Sartomer, SC Johnson & Son, Schmid Technology, Screenprint Dow, Secure Care Products Inc, Sefar Printing Solutions, Seiko Epson Corp, Sharp Laboratories of America, Sheldahl, Si-Cal Inc, SIFMAR - Solvay Industrial Foils, SKC, SmartSensor Telemed, SmartWrite, Smurfit Stone, Solicore , Soligie, Solvay, Southwall Technologies, Southwest Research Institute, Spectra, Spraylat, Steinerfilm, STMicroelectronics, Sun Chemical, Symmorphix , TDA Research, TempTime Corporation, Tetra Pak, Texas Instruments, The Marketing Store, The Technology Partnership, The Upper Deck Company, Thin Battery Technologies, Thin Film Electronics, Timestrip, T-Ink, Tobias Systems, Toppan Forms, Toppan Printing, Torrey Pines, Total Information , Toyobo , Transcore, Transilwrap , transNETics, Trident, Trierenberg, Tupperware, Tyco, Umicore, United Parcel Service, University of Cambridge, University of Colorado, University of Illinois, University of Kansas, University of Leeds, University of Pittsburgh, University of the Aegean, US Display Consortium, USG Corp, Valtronic SA, VDI Nachrichten, VDMA - OEA (Organic Electronics Association), Veeco Instruments SAS, Velcro Group Corp, VirtualBLUE, Vivid Print Innovations, VTT, Web Centric, Weyerhaeuser, Xaar, Xennia Technology, Xerox, Xink, YBC, Yuen Foong Yu Paper, Zebra, ZeroNine.